



2823

#5/Amor A
11/8/02
V8

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Koji Iketani et al.

Art Unit : 2823

Serial No. : 09/900,093

Examiner : Fernando L. Toledo

Filed : July 6, 2001

Title : SEMICONDUCTOR DEVICE MANUFACTURING METHOD

Commissioner for Patents
Washington, D.C. 20231RECEIVED
TECHNOLOGY CENTER 2800
OCT 31 2002RESPONSE

In response to the action mailed July 25, 2002, please amend the application as follows:

In the specification:

Please replace the title at beginning at page 1, line 1 with the following:

-- Method of Manufacturing Multiple Semiconductor Chips from a Single Wafer --

In the claims:

Please cancel claims 9 to 16.

Please amend claims 1 and 6 as follows:

1. (Amended) A method for manufacturing a semiconductor device comprising:
fixing semiconductor chips onto a substrate;
covering the semiconductor chips fixed onto the substrate with a common resin layer;
gluing an adhesive sheet onto the resin layer;
cutting the substrate and the resin layer in a state that the adhesive sheet is glued to the
resin layer; and
measuring the semiconductor devices in a state that the adhesive sheet is glued to the
resin layer.

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

October 24, 2002

Date of Deposit

Signature

Rose Papetti

Typed or Printed Name of Person Signing Certificate